



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE9255WSK		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA001593808						
<b>Package</b>		PG-DSO-14-39		<b>Weight*</b>		144.94 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.199	0.83	0.83	8275	8275
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		111	
	non noble metal	zinc	7440-66-6	0.065	0.04		445	
	non noble metal	iron	7439-89-6	1.290	0.89		8902	
wire	non noble metal	copper	7440-50-8	52.389	36.15	37.09	361464	370922
	noble metal	gold	7440-57-5	0.295	0.20	0.20	2035	2035
	encapsulation	organic material	carbon black	1333-86-4	0.175	0.12		1206
plastics		epoxy resin	-	8.040	5.55		55472	
	inorganic material	silicondioxide	60676-86-0	79.176	54.62	60.29	546282	602960
leadfinish	non noble metal	tin	7440-31-5	1.226	0.85	0.85	8460	8460
plating	noble metal	silver	7440-22-4	0.552	0.38	0.38	3808	3808
glue	plastics	epoxy resin	-	0.128	0.09		885	
	noble metal	silver	7440-22-4	0.385	0.27	0.36	2655	3540
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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